

Title (en)

Method and apparatus for creating thin walls in the ground.

Title (de)

Verfahren und Vorrichtung zur Herstellung von dünnen Wänden im Boden.

Title (fr)

Procédé pour la réalisation de parois minces dans le sol et dispositif pour sa mise en oeuvre.

Publication

EP 0513461 B1 19950510 (FR)

Application

EP 91402175 A 19910802

Priority

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Abstract (en)

[origin: EP0513461A1] The invention relates to a method and apparatus for creating continuous thin walls in the ground, of the type in which a vertical beam or sheet pile, which comprises at its lower part a device for injecting a grout into the ground, which grout, after solidifying, forms the thin wall, is driven successively into the ground, along the route of the wall being built, using vibratory means. Method characterised in that at least one jet (12) of liquid at very high pressure, directed substantially in the plane of the wall to be built, is sent to the lower part of the beam (1).
<IMAGE>

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